

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
CHIH-TSUNG SHIH	07/07/2015
SHINN-SHENG YU	07/07/2015
JENG-HORNG CHEN	07/08/2015
ANTHONY YEN	07/07/2015
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
<b>Street Address:</b>	NO. 8, LI-HSIN ROAD 6
<b>Internal Address:</b>	SCIENCE-BASED INDUSTRIAL PARK
<b>City:</b>	HSIN-CHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-77
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14799616
<b>CORRESPONDENCE DATA</b>	
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<b>Correspondent Name:</b>	HAYNES AND BOONE, LLP IP SECTION
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<b>ATTORNEY DOCKET NUMBER:</b>	P20140715US00/24061.3074
<b>NAME OF SUBMITTER:</b>	ERIC Q. LI
<b>SIGNATURE:</b>	/Eric Q. Li/
<b>DATE SIGNED:</b>	07/15/2015
<b>Total Attachments: 2</b>	

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Docket No.: P20140715US00 / 24061.3074  
Customer No.: 42717

### ASSIGNMENT

WHEREAS, we,

- |     |                 |    |   |
|-----|-----------------|----|---|
| (1) | Chih-Tsung Shih | of | 7F., No. 2, Nanzhong St., North Dist.<br>Hsinchu City 300, Taiwan, R.O.C. |
| (2) | Shinn-Sheng Yu  | of | 4F-2, No. 16, Lane 634, Nanda Rd.<br>Hsinchu, Taiwan, R.O.C.              |
| (3) | Jeng-Horng Chen | of | 1, Alley 2, Lane 45, Fu-Chyun Str.<br>Hsin-Chu, Taiwan, R.O.C.            |
| (4) | Anthony Yen     | of | 20F-9, 188 Guanxin Road<br>Hsinchu, 300, Taiwan, R.O.C.                   |

have invented certain improvements in

### PELLICLE FOR EUV MASK AND FABRICATION THEREOF

for which we have filed an application for Letters Patent of the United States of America on \_\_\_\_\_, and assigned U.S. Serial number \_\_\_\_\_; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

WIT:

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

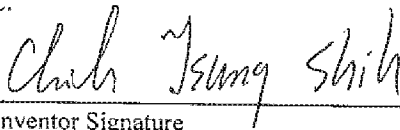
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AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chih-Tsung Shih

Residence Address: 7F., No. 2, Nanzhong St., North Dist.  
Hsinchu City 300, Taiwan, R.O.C.

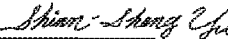
Dated: 7/7/2015

  
Inventor Signature

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Residence Address: 4F-2, No. 16, Lane 634, Nanda Rd.  
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Dated: 7/7/2015

  
Inventor Signature

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Dated: 7/8/2015

  
Inventor Signature

Inventor Name: Anthony Yen

Residence Address: 20F-9, 188 Guanxin Road  
Hsinchu, 300, Taiwan, R.O.C.

Dated: 7/7/15

  
Inventor Signature